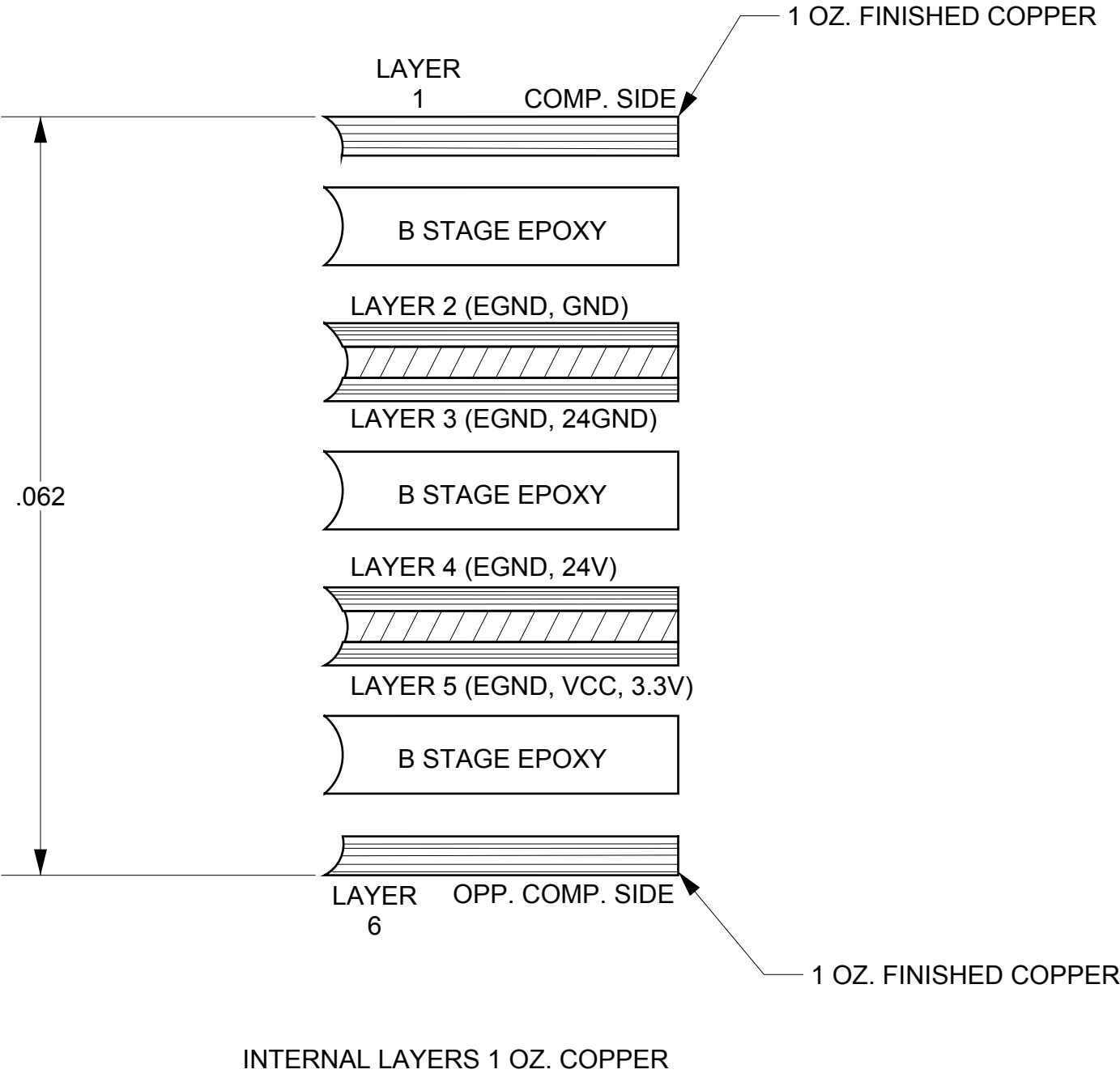
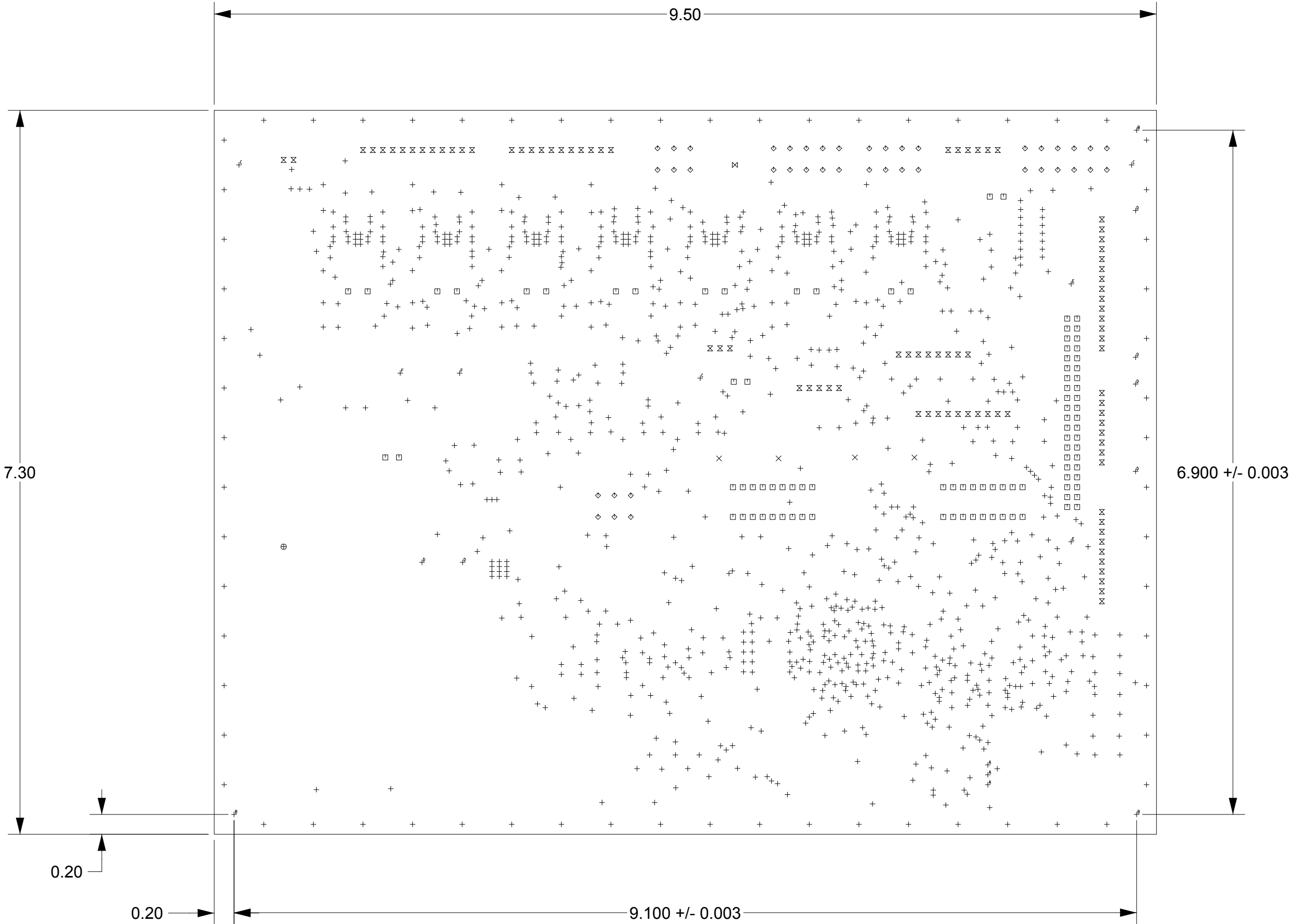


FINISHED HOLE SIZE TABLE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Min/Max
⊕	0.010	1082	Yes	+0/-0.010
⊕ ^A	0.015	3	Yes	+0/-0.015
□	0.038	96	Yes	+/-0.003
⊗	0.042	89	Yes	+/-0.003
⊗	0.052	4	Yes	+/-0.003
◇	0.055	42	Yes	+/-0.003
⊕ ^F	0.149	2	Yes	+/-0.004
⊗	0.157	1	Yes	+/-0.004
⊕ ^E	0.116	2	No	+/-0.003
⊕ ^B	0.125	3	No	+0.002/-0
⊕ ^D	0.134	6	No	+/-0.004
⊕ ^C	0.157	3	No	+/-0.004
⊕	0.163	1	No	+/-0.004
Total		1334		



NOTES :

- 1.0 RoHS: PCB MUST COMPLY WITH WATERS RoHS REQUIREMENTS DOCUMENT 735001207.
- 2.0 MATERIAL:
 - 2.1 MATERIAL TO BE IN ACCORDANCE WITH IPC-4101/99 OR BETTER.
 - 2.2 MATERIAL SHALL HAVE A DECOMPOSITION TEMPERATURE OF >=325 DEGREES C WITH CTE <=3.5% FROM AMBIENT TO 288 C AND SURVIVE 6 ASSEMBLY REFLOW EXCURSIONS.
 - 2.3 MANUFACTURER MAY ADD THIEVING TO EXTERNAL LAYERS TO IMPROVE COPPER DISTRIBUTION FOR PLATING. THIEVING MUST BE A MINIMUM OF .150 FROM ANY DESIGN FEATURE AND NO THIEVING IS ALLOWED UNDER ANY SURFACE MOUNT COMPONENTS.
- 3.0 SURFACE FINISH:
 - 3.1 ELECTROLESS NICKEL IMMERSION GOLD (ENIG) 2 - 8 MICRO INCHES OF GOLD OVER 100 - 250 MICRO INCHES OF NICKEL, PER IPC-4552.
- 4.0 SOLDERMASK:
 - 4.1 ALL VIAS TO BE PLUGGED FROM THE PRIMARY SIDE WITH SOLDERMASK OR EQUIVALENT PRODUCT PRIOR TO FINAL SOLDERMASK APPLICATION AS PER IPC-4761 TYPE IV-a VIA.
 - 4.2 SOLDERMASK OVER BARE COPPER (SMOBC).
- 5.0 PRINTED CIRCUIT BOARD FABRICATION NOTES AND REGULATORY REQUIREMENTS TO COMPLY WITH WATERS DOCUMENT NUMBER 735001870.
- 6.0 USE ARTWORK PHOTO 610000416 REV E FOR BOARD FABRICATION.

UNLESS OTHERWISE SPECIFIED All dimensions are in inches. Remove all burrs and break sharp edges. Tolerances: Decimals .XX = ± .01 .XXX = ± .005 Angles = ± 0°30' SURFACE ROUGHNESS 63✓	DESIGN B. DEGUIRE	DATE 04-MAY-2018	Waters 34 Maple St. Milford MA 01757 USA		
	DRAWN B.ALEXANDER	DATE 04-MAY-2018			
	ENGR	DATE	PCB 2690 FLUIDICS ROHS		
	ENGR	DATE			
	APPROVED	DATE	SIZE DWG NO		
DO NOT SCALE PRINT			D	510000416	REV E
			SCALE 1 : 1	MENTOR EXPEDITION	SHEET 1 OF 1